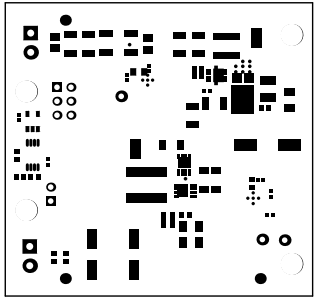
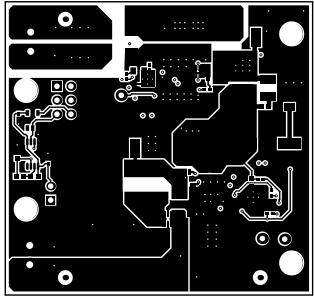


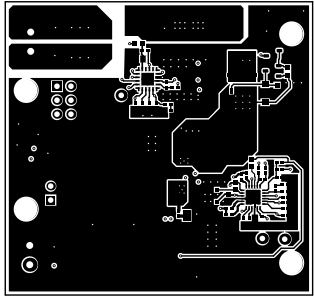
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15041C	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 2/9/2018	6:17:26 PM	TEXAS INSTRUMENTS



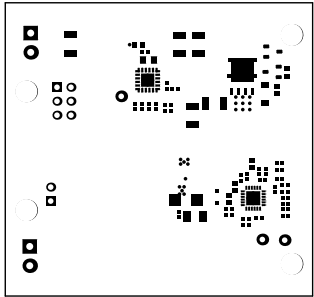
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15041C	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 2/9/2018 6:17:27 PM		TEXAS INSTRUMENTS



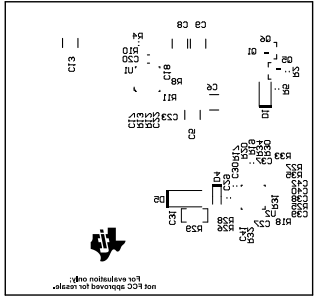
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15041C	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 2/9/2018	6:17:28 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15041C	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 2/9/2018	6:17:29 PM	TEXAS INSTRUMENTS

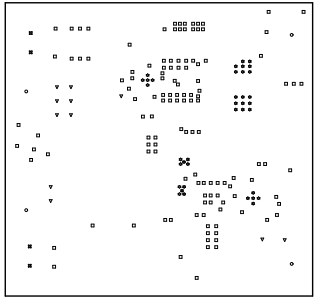


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15041C	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 2/9/2018 6:17:30 PM		TEXAS INSTRUMENTS

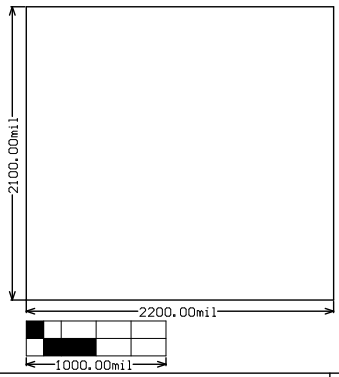


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15041C	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 2/9/2018	6:17:31 PM	TEXAS INSTRUMENTS

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
○	4	199.00mil (4.029mm)	NPTH	Round	Top Layer - Bottom Layer	
⊗	37	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	
□	127	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
▽	11	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	4	50.00mil (1.270mm)	PTH	Round	Top Layer - Bottom Layer	
	183 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15041C	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 2/9/2018	6:17:32 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15041C	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 2/9/2018	6:17:33 PM	TEXAS INSTRUMENTS

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